







	MATED HEIGHT TAI	BLE
DIM. A	RECPT. ASSY. P/N	PLUG ASSY. P/N
6.0	10026846-X01	10022671-X02

MATED HEIGHT AFTER REFLOW IS BASED ON Ø .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

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END	VIEW	_	MATED	CONNECTORS	SCALE NONE

mat'	mat´l. code				surfa	surface /			tolerance			ction		product family												
	SEE NOTE 1					ASME Y14.5 ✓			Y14.5				MEG-Array													
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form: A4mmXLc

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SPOW Printed: NOTATION Printed: Dec 13, 2012

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NOTES:

(1.) <u>MAT'L:</u>

HOUSING: LCP

CONTACT: COPPER ALLOY

PLATING:

CONTACT: (SEE TABLE ON SHEET3) SOLDER BALL: (SEE TABLE ON SHEET3) EUTECTIC SnPb OR LEAD FREE 95.5Sn/4Ag/0.5Cu

- (2.) SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- (3.) MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.

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- (4.) PLATING FOR INDICATED -2XX SERIES PRODUCT NUMBER MEET THE REQUIREMENTS OF GR-1217-CORE, CENTRAL OFFICE ENVIRONMENT, (25 YEAR LIFE EXPECTANCY).
- (5.) PLATING FOR INDICATED -2XX SERIES PART NOS. IS AU OVER NI WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
- (6.) KNIT LINE: SLIGHT VISIBLE MARKS (USUALLY A LINE) INDICATING THE DIRECTION AND MEETING POINT OF PLASTIC RESIN FLOW FRONTS TRAVELING AROUND ANY OBSTRUCTIONS TO THE RESIN FLOW VIA THE REQUIRED MOLD TOOLING.
- (7.) FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THERFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- (8.) THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

11. A D SYMBOL WILL BE NEXT TO ANY DIMENSION, NEW VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION

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